

Title (en)

CURABLE ORGANOSILICON RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

Title (de)

HÄRTBARE ORGANOSILICIUMHARZZUSAMMENSETZUNG UND HALBLEITERBAUELEMENT

Title (fr)

COMPOSITION EN RÉSINE D'ORGANOSILICIUM DURCISSABLE ET DISPOSITIF SEMI-CONDUCTEUR

Publication

**EP 3587497 B1 20210505 (EN)**

Application

**EP 19181120 A 20190619**

Priority

JP 2018124806 A 20180629

Abstract (en)

[origin: EP3587497A1] A curable organosilicon resin composition is provided comprising (A) an organopolysiloxane of block polymer structure consisting of 30 to 80 mol% of  $R^{1/3}SiO_{3/2}$ , 10 to 70 mol% of  $R^{2/2}SiO_{2/2}$  and 0 to 30 mol% of  $R^{3/3}SiO_{1/2}$  units, having Mw of 5,000-100,000, and containing at least a part of the  $R^{2/2}SiO_{2/2}$  unit having an average number of 3 to 80 repetitions, at least two silicon-bonded alkenyl groups per molecule, 0.001 to 1.0 mol/100 g of silicon-bonded hydroxyl groups, and up to 1.0 mol/100 g of silicon-bonded alkoxy groups, (B) an organohydrogenpolysiloxane containing at least two SiH groups and at least one silicon-bonded aryl group per molecule, and (C) a hydrosilylation catalyst.

IPC 8 full level

**C08L 83/04** (2006.01); **H01L 33/10** (2010.01)

CPC (source: EP US)

**C08G 77/44** (2013.01 - US); **C08L 83/04** (2013.01 - EP US); **H01L 33/56** (2013.01 - EP); **C08G 77/12** (2013.01 - EP); **C08G 77/16** (2013.01 - EP); **C08G 77/20** (2013.01 - EP); **C08G 77/80** (2013.01 - EP); **C08L 2203/20** (2013.01 - US)

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DOCDB simple family (publication)

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DOCDB simple family (application)

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